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For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

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APPLICATION DATA SHEET

(1) APPLICANT INFORMATION

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(3) APPLICANT INFORMATION

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(4) REPRESENTATIVE INFORMATION

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(5) DOMESTIC PRIORITY INFORMATION

This case is a Divisional of USPTO Serial Number 09/321,565, filed May 28, 1999 and issuing as US Patent No. 6,221,682 on April 24, 2001.

(6) FOREIGN PRIORITY INFORMATION

None

(7) ASSIGNEE INFORMATION

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